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TECHNOLOGY CENTER 2800

Applicant: ABBOTT Art Unit: 2826

Serial No.: 09/525,105 Examiner: Williams, A.

Filed: 03/14/00 Docket: TI-28098

For: "SEMICONDUCTOR CIRCUIT ASSEMBLY HAVING
A PLATED LEADFRAME INCLUDING GOLD SELECTIVELY
COVERING AREAS TO BE SOLDERED"

AMENDMENT 37 CFR 1.115

June 28, 2001

Assistant Commissioner
for Patents
Washington, D.C. 20231

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Deposit: June 28, 2001. I hereby certify that this paper is being deposited with the
U.S. Postal Service Express Mail Post Office to Addressee Service under 37 CFR 1.10 on
the date shown above and is addressed to the Assistant Commissioner for Patents,
Washington, D.C. 20231.

Glenda West

Sir:

Responsive to the Office Action of March 28, 2001, please amend the application
as follows:

Change the title to read:

"SEMICONDUCTOR CIRCUIT ASSEMBLY HAVING A PLATED
LEADFRAME INCLUDING GOLD SELECTIVELY COVERING AREAS TO
BE SOLDERED"

Amend the claims as follows:

Claim 1, line 3, after "covering" insert—outer—; line 4, after "attachment", insert
a period— and delete the remainder of the claim.